

LCGT design review

Cryogenic suspension
Heat link design
Temperature

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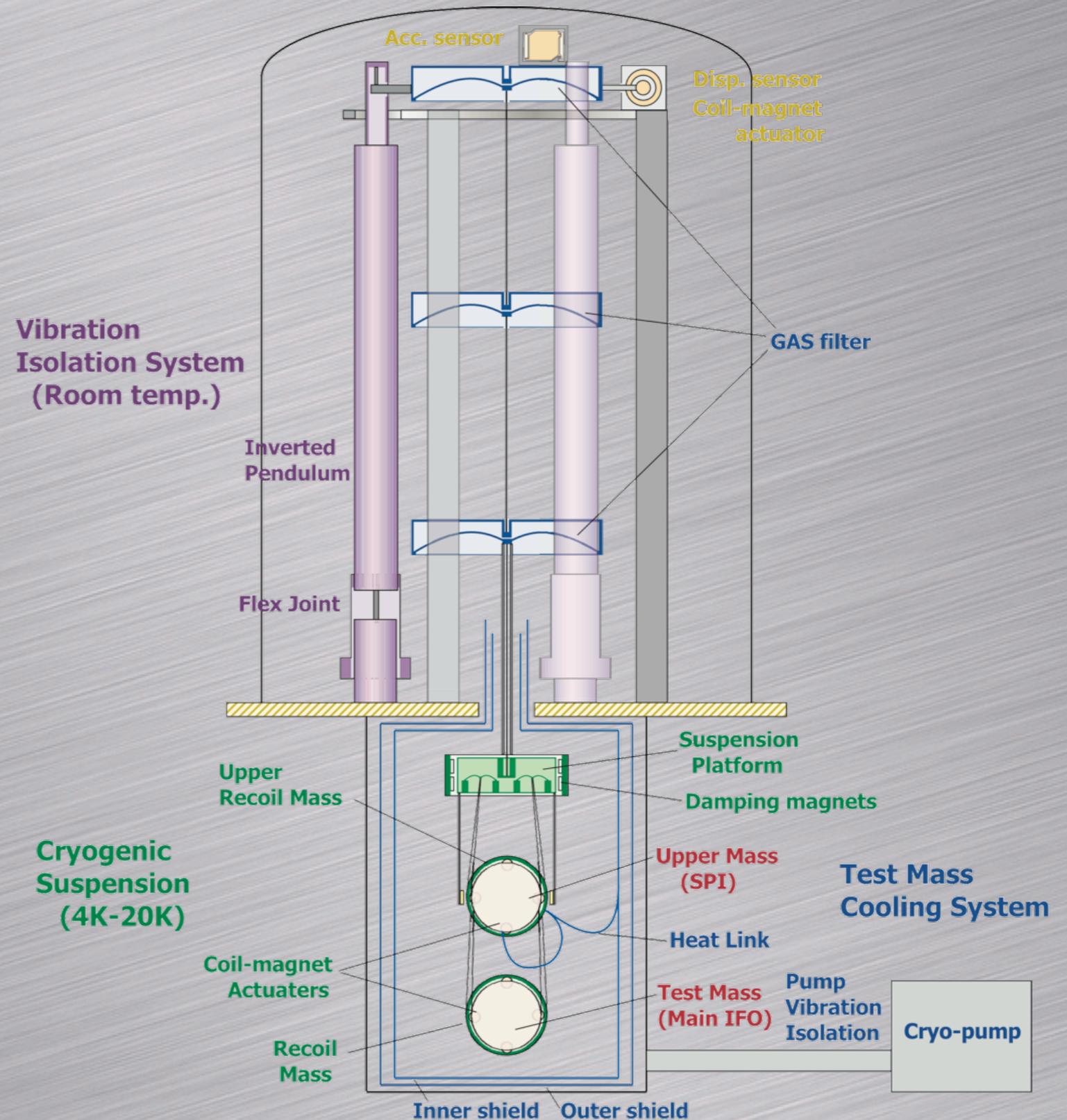
2004/04/27 revised

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- Flowchart of designs
- Point mass model
- Sapphire mirror cooling
- Heat link design
- Summary

What is designed?

- The cryogenic suspension is referred to the picture.
- Temperature distribution.
- Major item is the heat links design.



Flowchart of designs

Point mass model of the cryogenic suspension

heat in the mirror
mirror temperature
thermal conductivity

Cooling mirror by sapphire fibers

Temperature of upper mass

Heat link design

Temp. of cryostat
length of heat link
thermal conductivity

Minimum cross section

change diameter of wires

Number of the wires
vibration isolation ratio

No

estimate seismic noise

satisfied

Goal!!

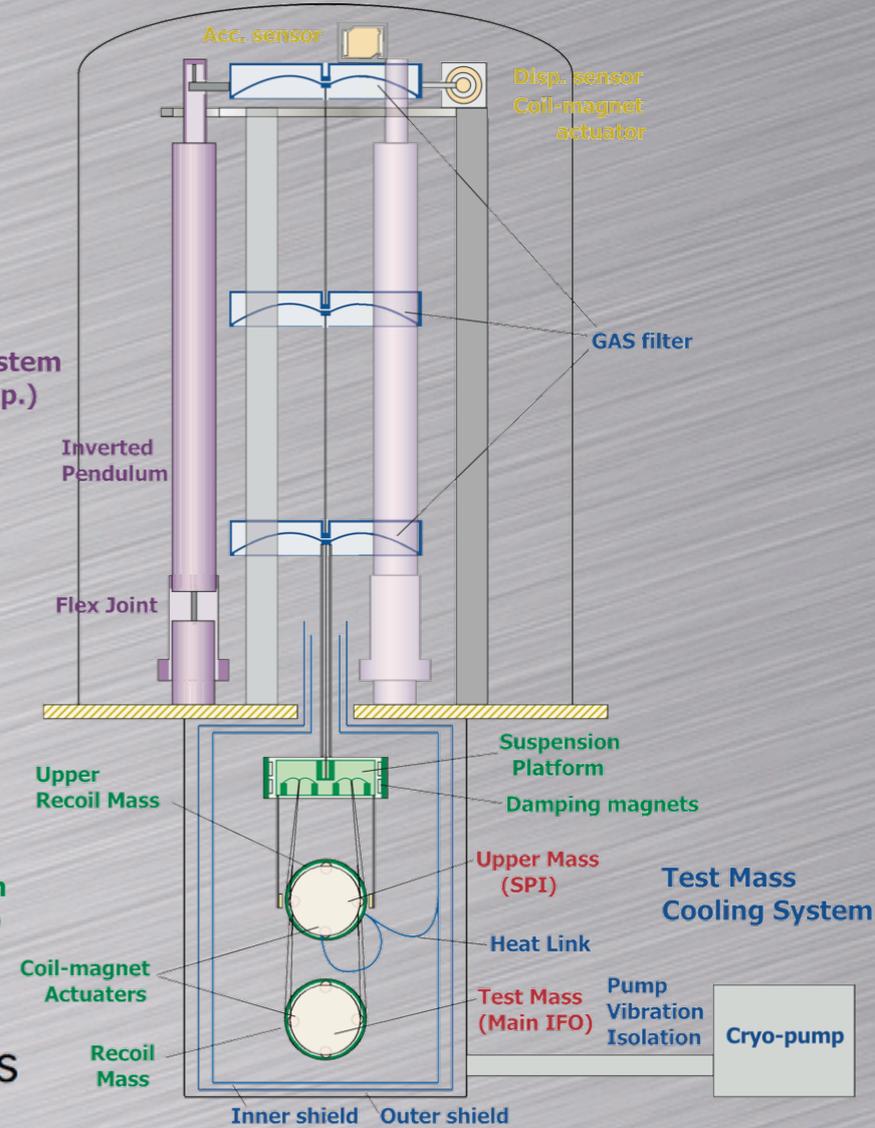
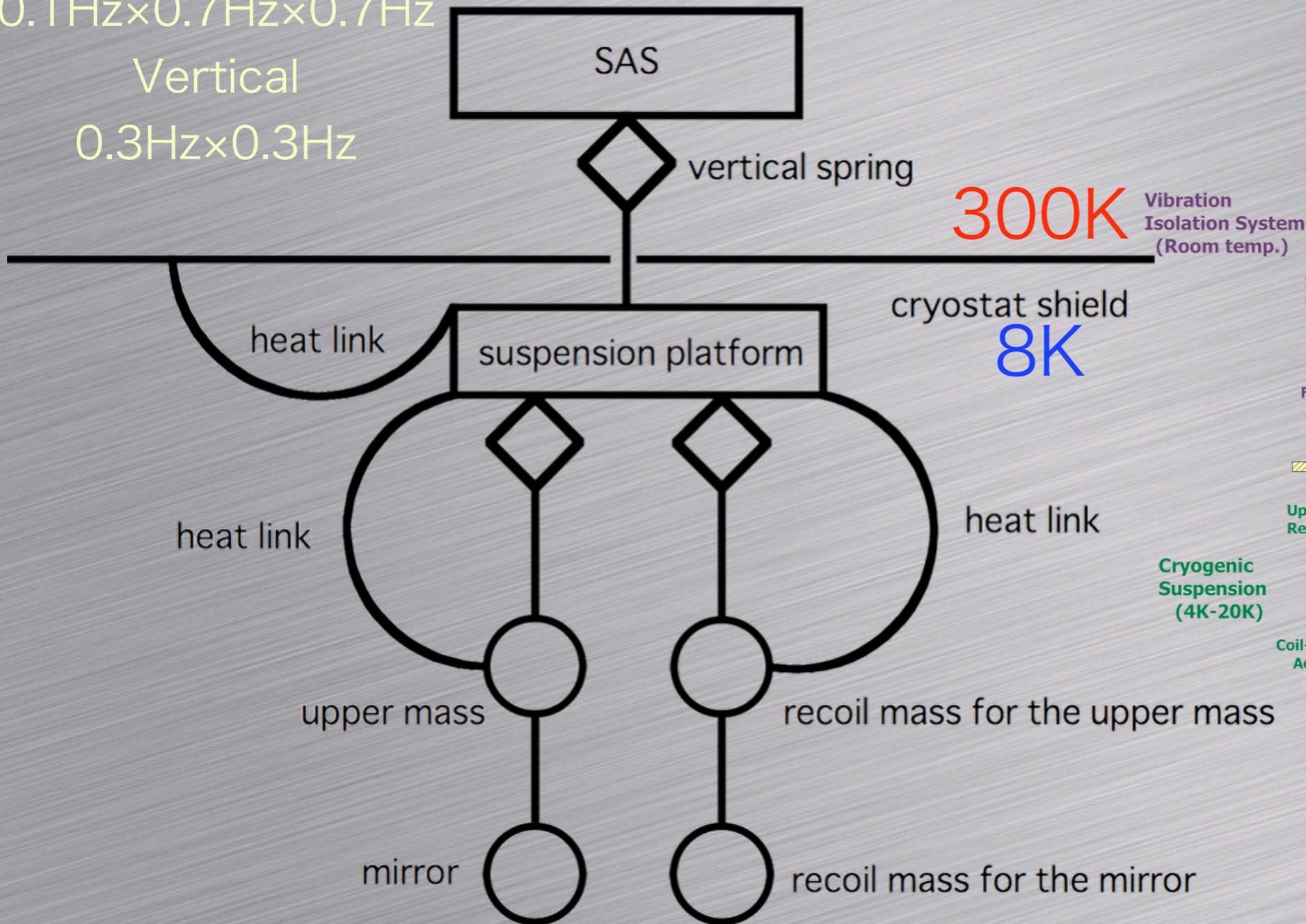
Point mass model

Horizontal

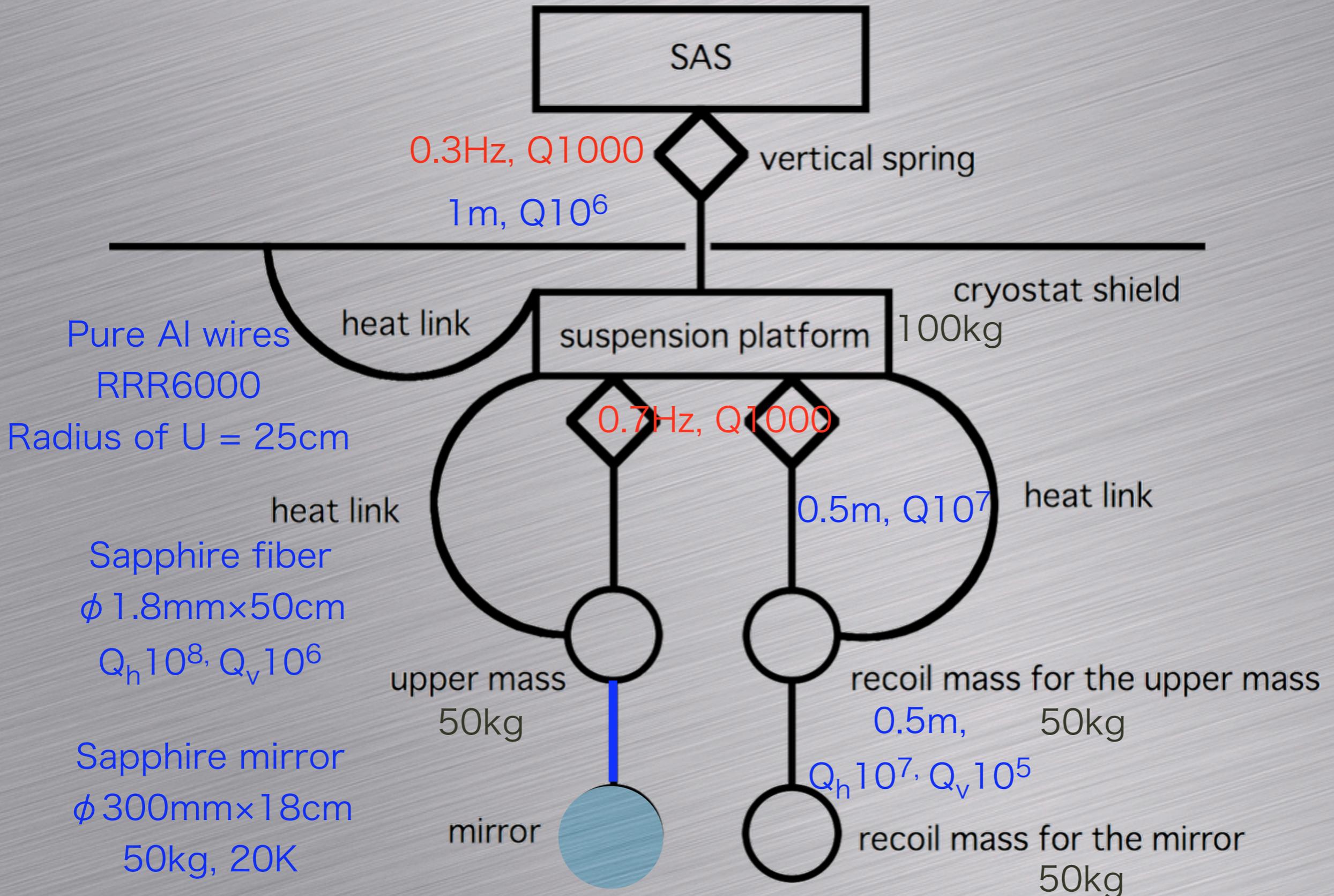
$0.1\text{Hz} \times 0.7\text{Hz} \times 0.7\text{Hz}$

Vertical

$0.3\text{Hz} \times 0.3\text{Hz}$



Point mass model 2



Sapphire mirror cooling

- The mirror substrate
 - Sapphire cylinder
 - 50 kg, ϕ 300×180
 - cooled under 20K
- The sapphire fiber suspension
 - 4 wires, ϕ 1.8×500
 - Sapphire - Sapphire bonding technique

Sapphire mirror cooling 2

● - heat in the mirror-

● Laser absorption in the substrate

- 20 ppm/cm laser absorption ratio.

- 360 mW

● Laser absorption in the coating

- 0.1 ppm laser absorption ratio.

- 40mW

● Other heat source

- radiation from laser holes..... not considered.

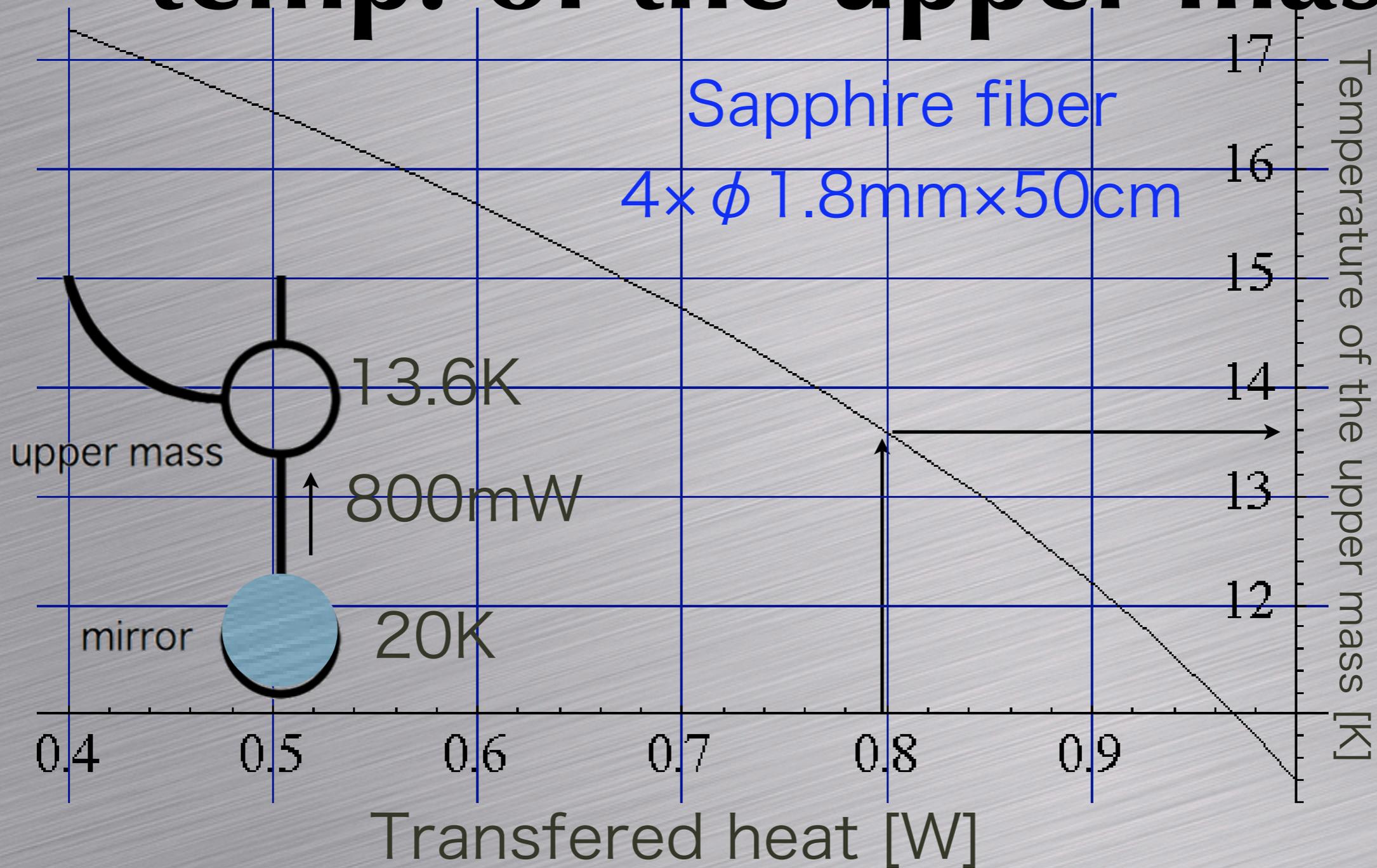
● Margin

$$800 \text{ mW} = 2 \times (360 \text{ mW} + 40 \text{ mW})$$

is design heat.

Sapphire mirror cooling 3

- temp. of the upper mass-

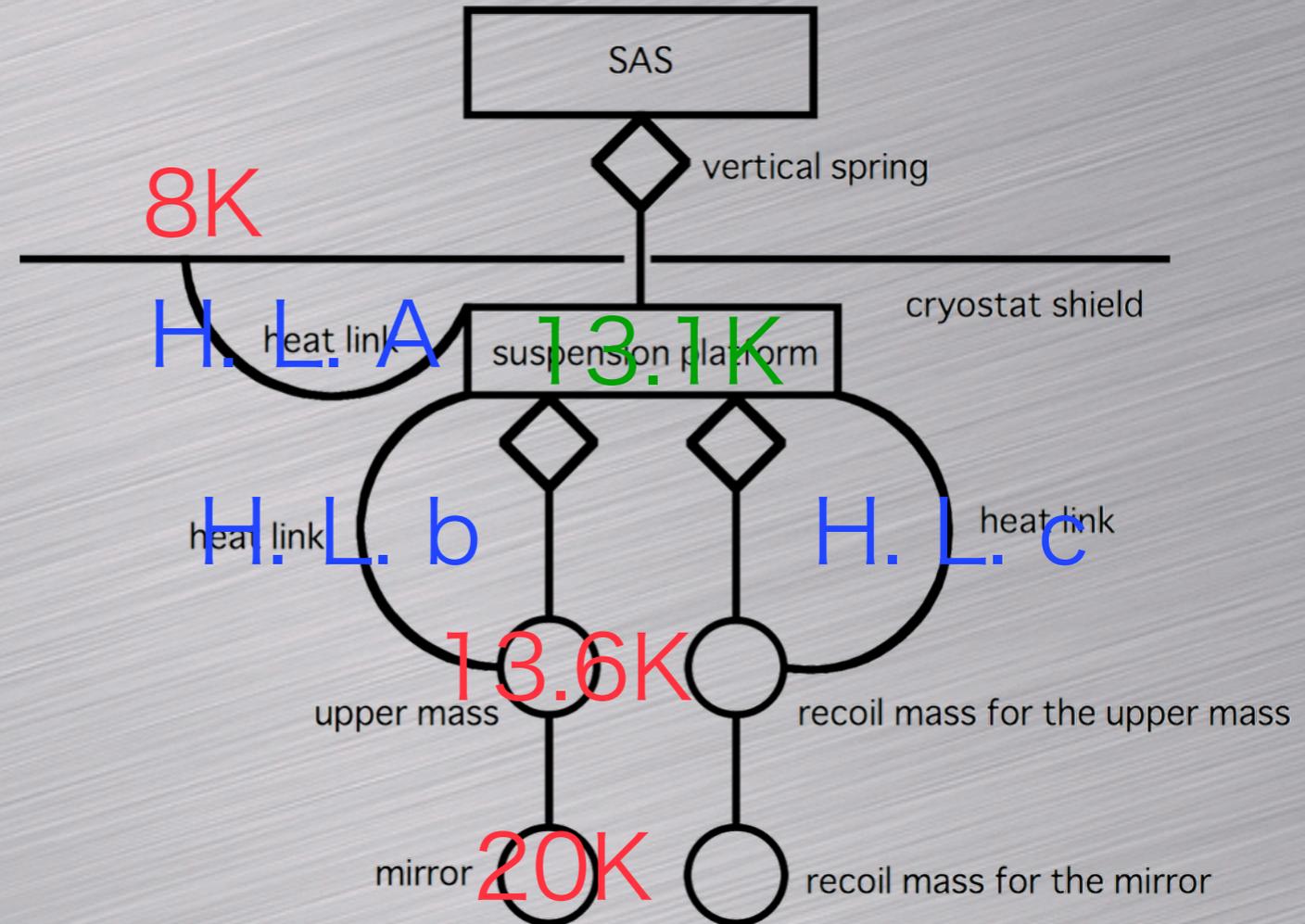


Temperature of the upper mass is **13.6K**.

Heat link design

-3 heat links-

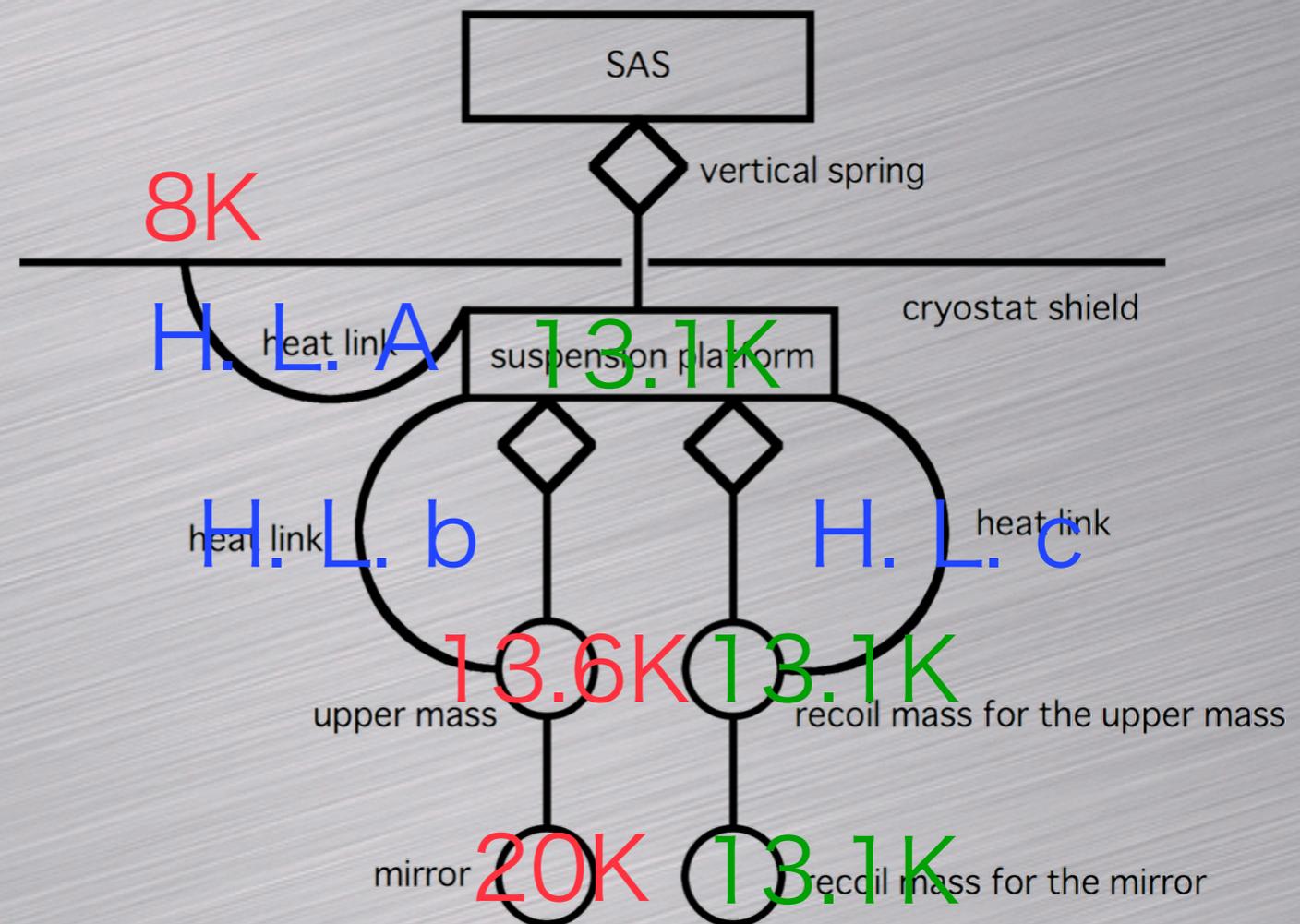
- H. L. A
 - vibration isolation
 - thermal conduction
 - large temperature difference.
- H. L. b & c
 - thermal conduction



Heat link design 2

-heat of coil-

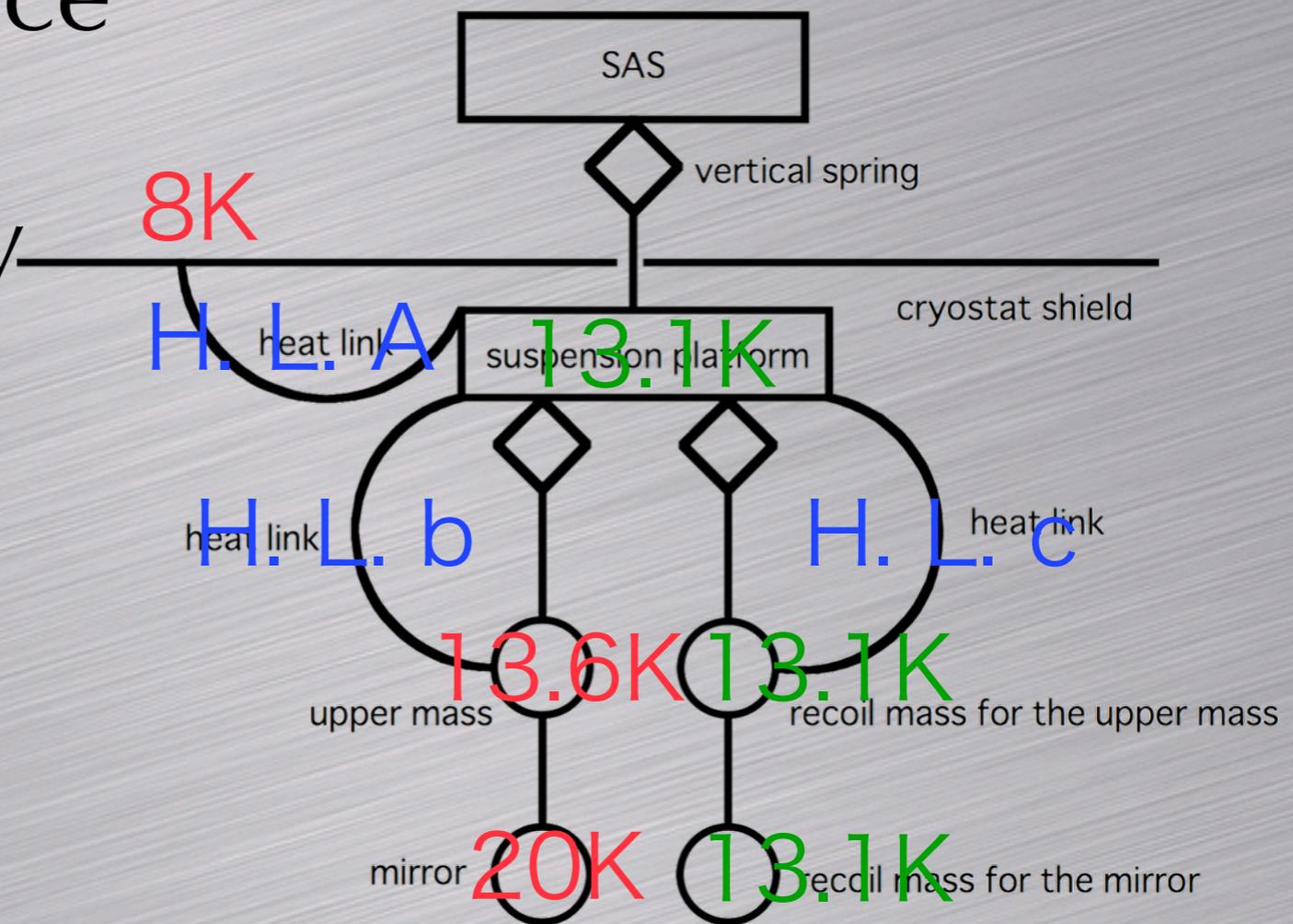
- If use **high RRR** Al or Cu wire for the coils, heat in the coils may be **mW**.
- 300K: $1\text{A} \times 1\text{V} = 1\text{W}$
- 4K: $\text{RRR} = 1000$, $1\text{A} \times 1\text{mV} = 1\text{mW}$
- At present, the heat in the coils is **not considered**.
- H. L. b = c in the design.



Heat link design 3

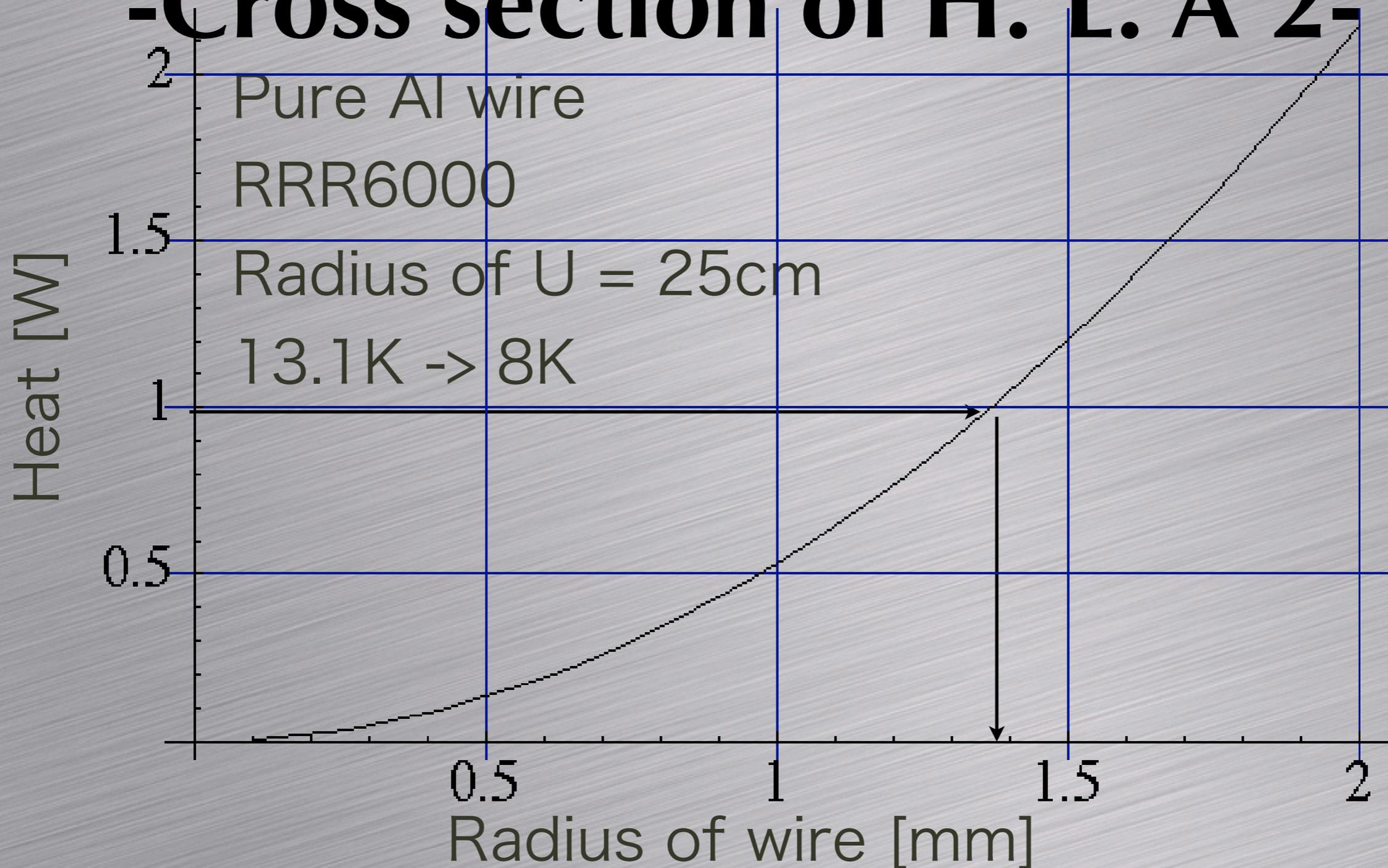
-Cross section of H. L. A-

- Temperature difference
 - 13.1K -> 8K
- Thermal conductivity
 - RRR6000, pure Al wire
- Length of wire
 - radius of U = 25cm
 - 0.8m
- Heat
 - 1W=800mW + SPI + etc.



Heat link design 4

-Cross section of H. L. A 2-



Radius of **1.4 mm** is needed.

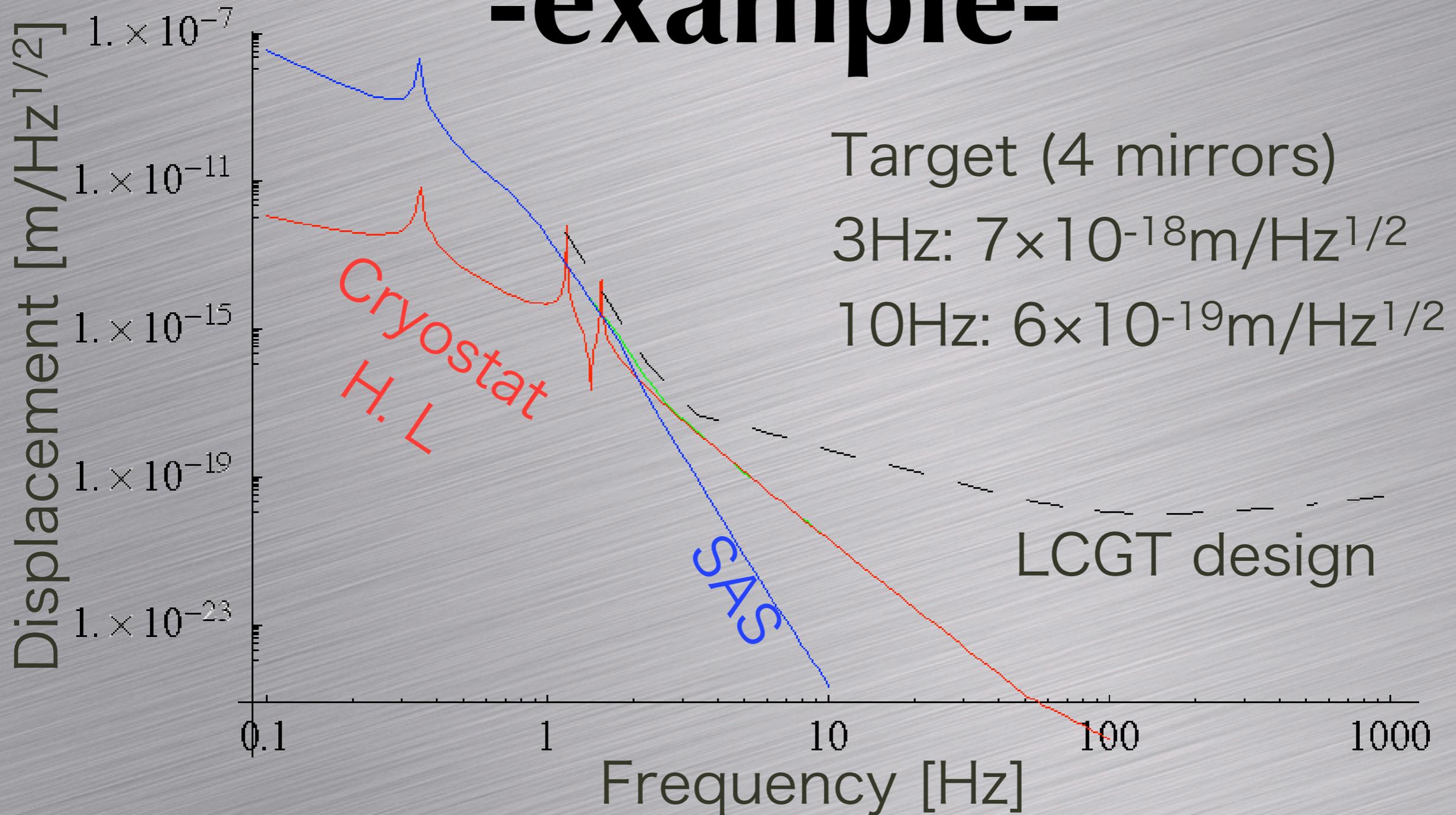
Heat link design 5

-seismic noise-

- Change diameter and number of wires.
 - must keep cross section for cooling.
- Estimate seismic noise at the mirror.
 - X (light axis), Y, Z direction.
- SAS is excited by **normal Kamioka level**.
- Cryostat is vibrating **10 × Kamioka level**.
- SPI: **-40 dB** isolation ratio in both X & Z.
- Coupling: **1%** is assumed in both Y & Z.
- Design two cases: **3Hz** cross & **10Hz** cross.
- H. L. b & c are **not important** for seismic noise.

Heat link design 6

-example-

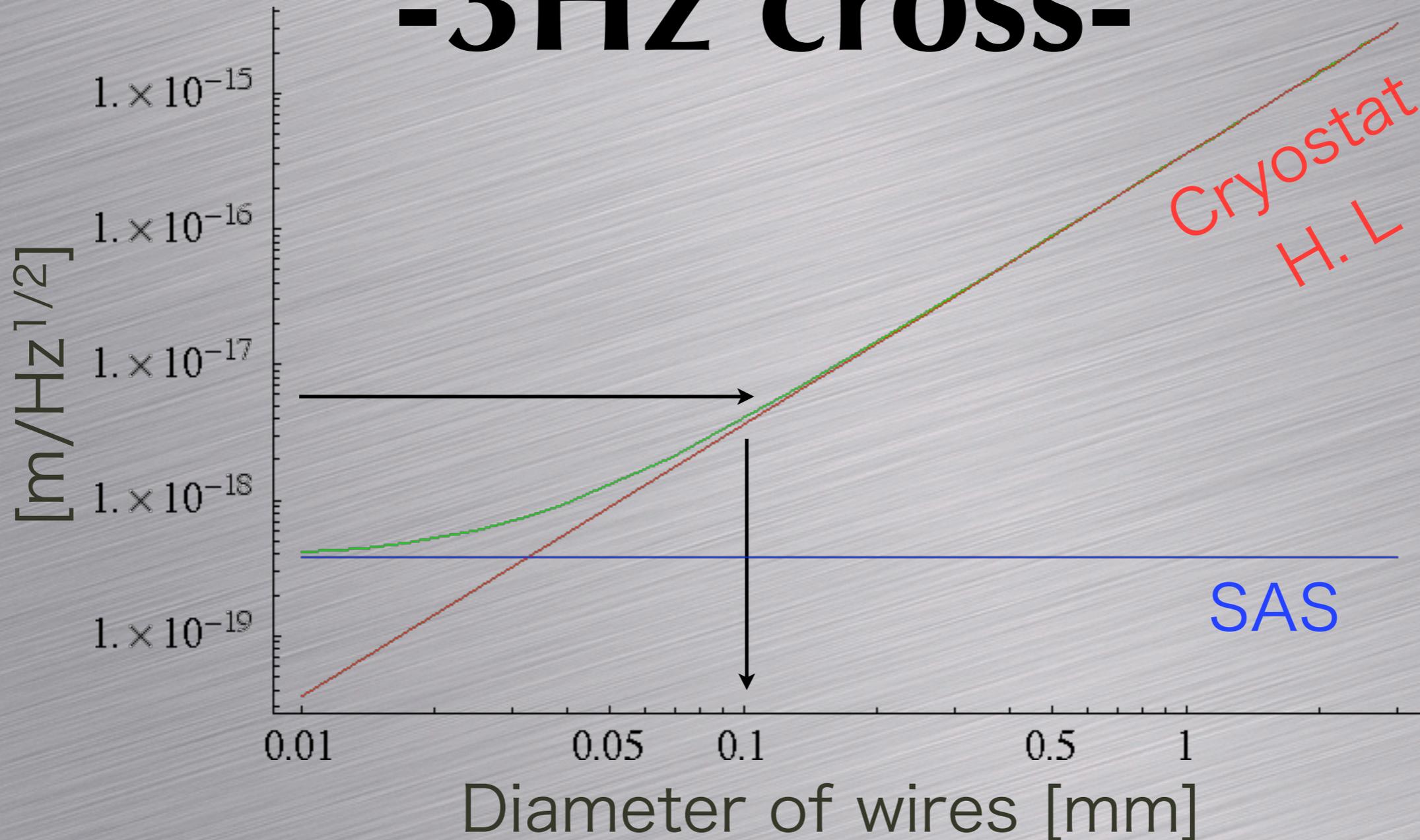


Search for optimal diameter for H. L. wires.

Heat link design 6

-3Hz cross-

Displacement at 3Hz

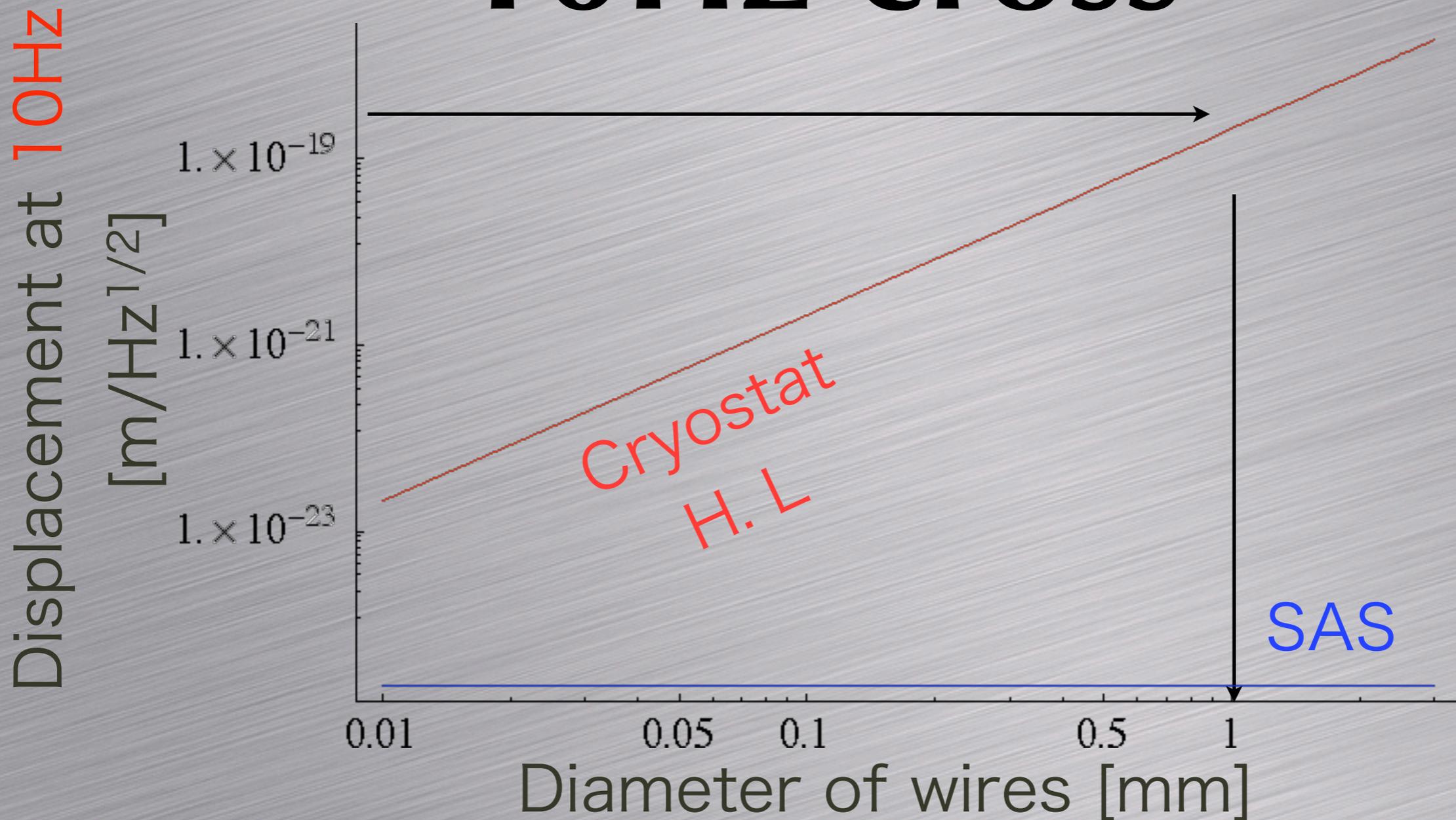


Diameter of **0.1mm** is satisfied.

Number of wires **800**.

Heat link design 7

-10Hz cross-

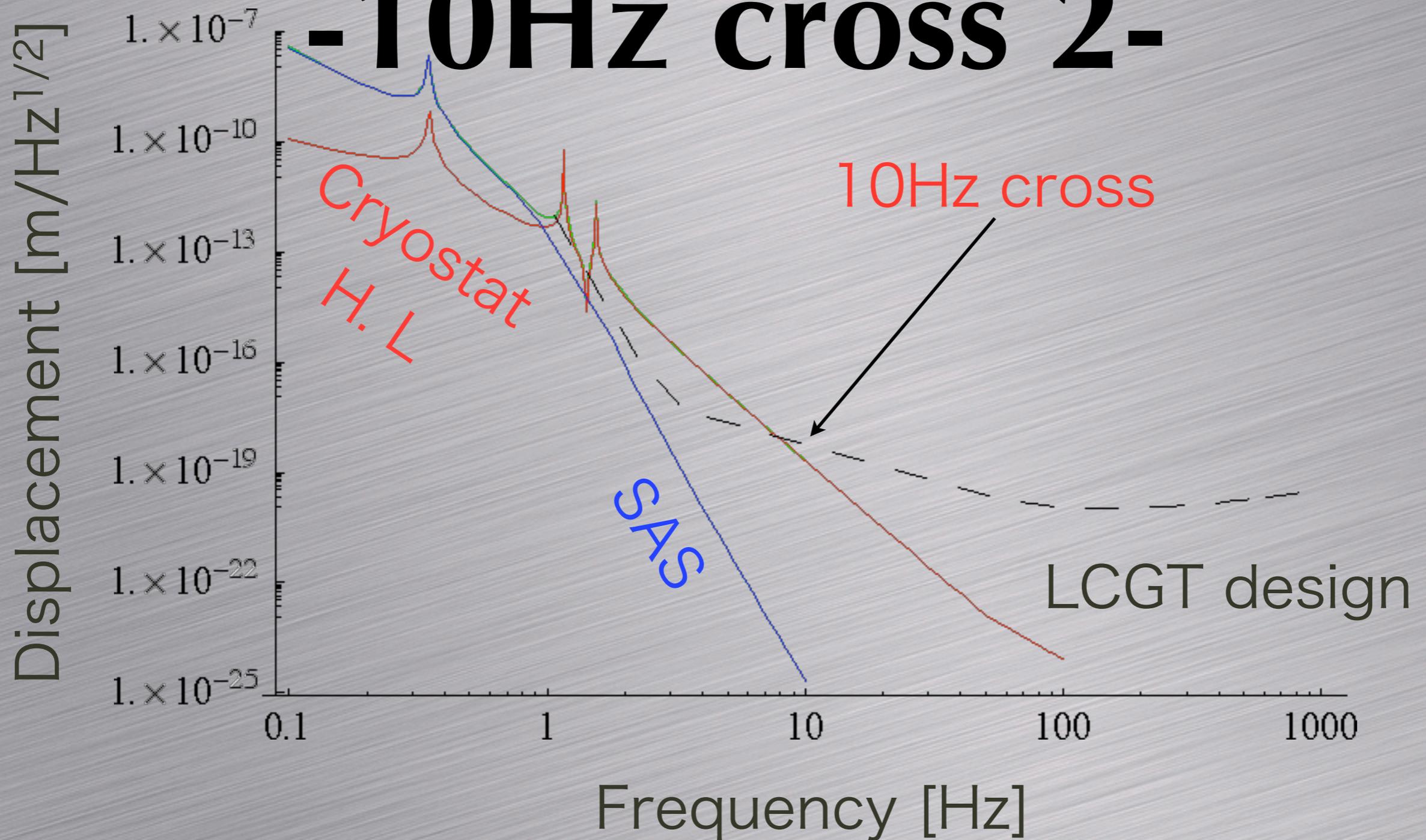


Diameter of 1mm is satisfied.

Number of wires 8.

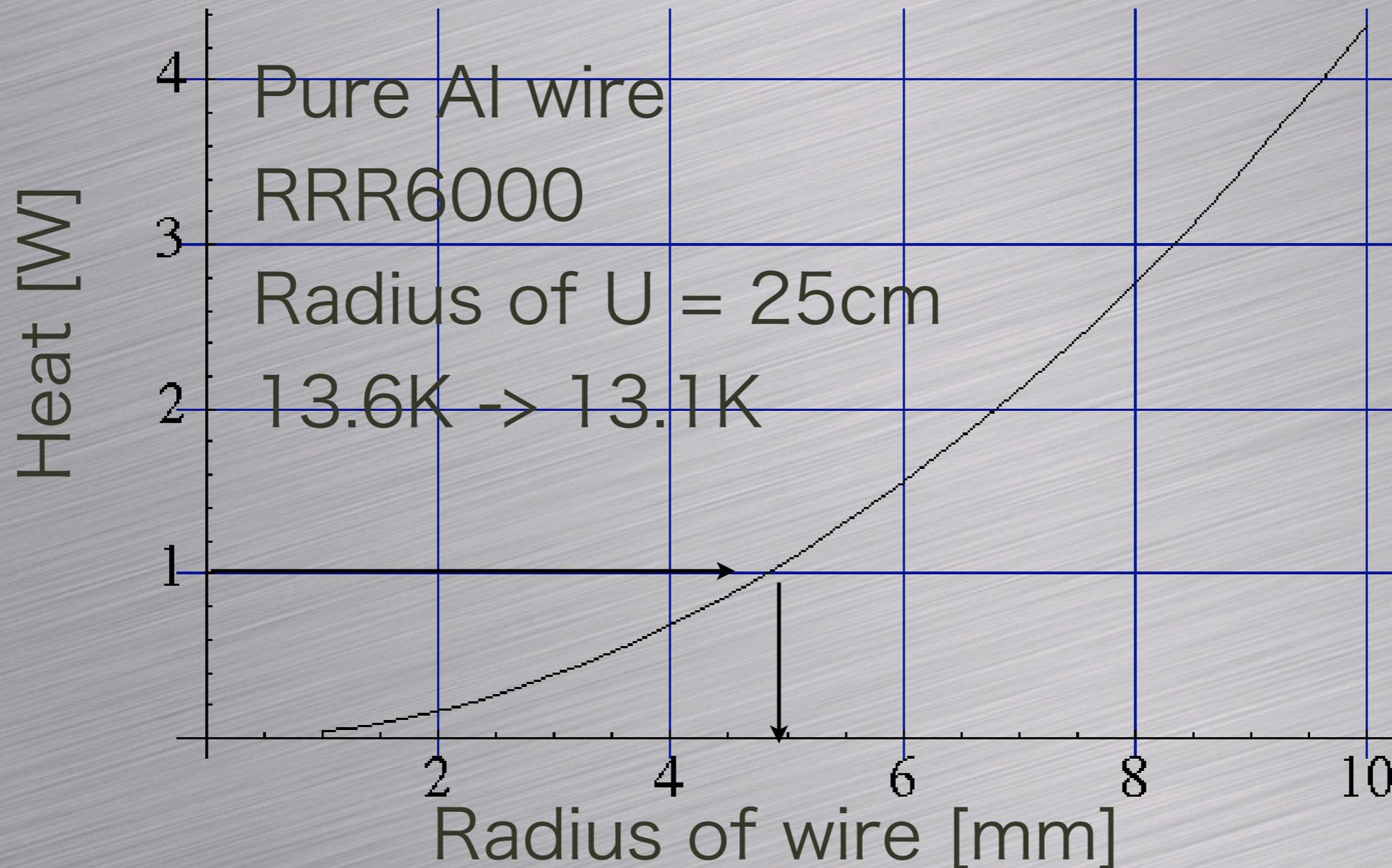
Heat link design 8

-10Hz cross 2-



Heat link design 9

-cross section H. L. b &c-

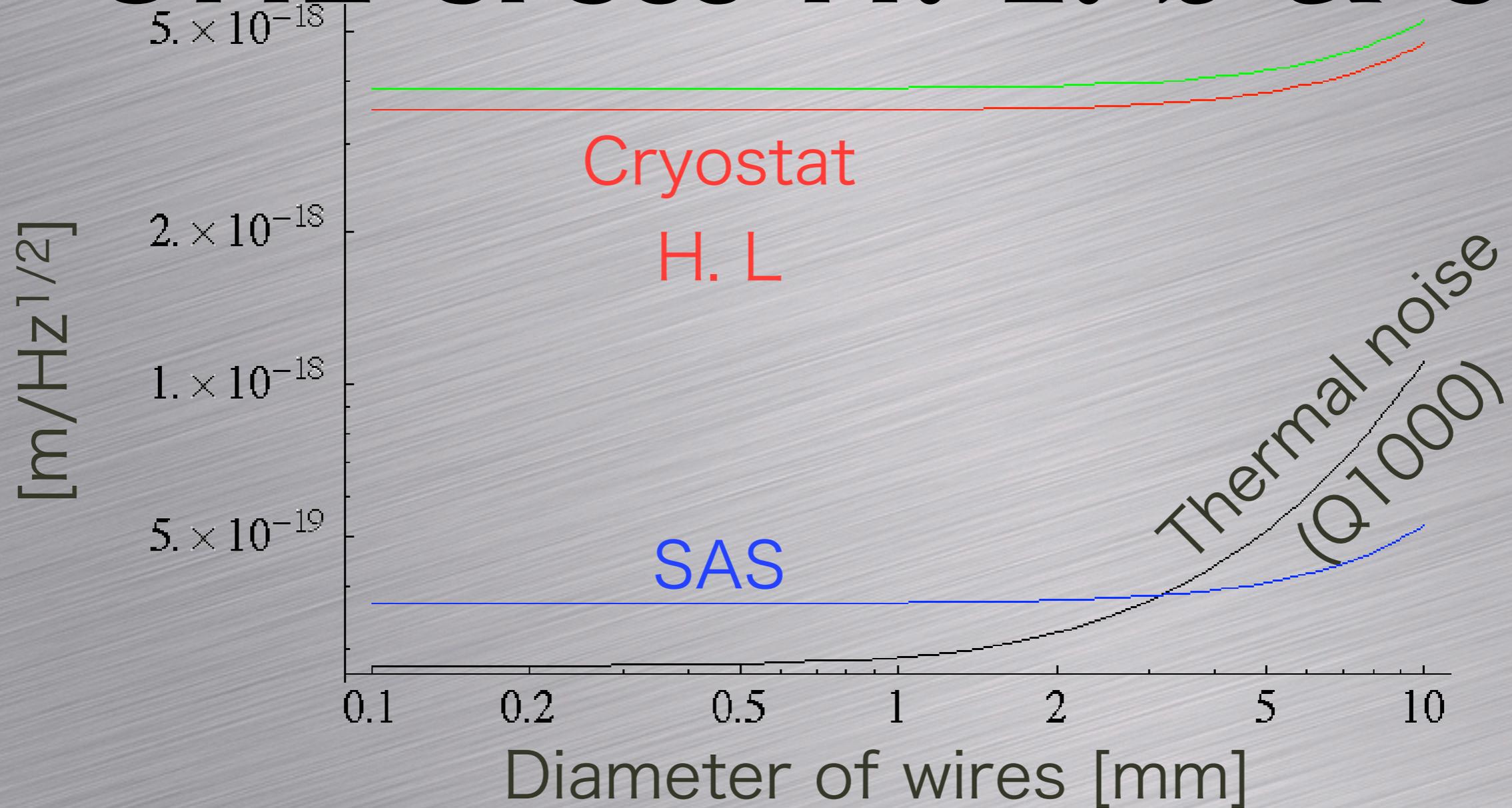


Radius of **5 mm** is needed.

Heat link design 10

-3Hz cross H. L. b & c-

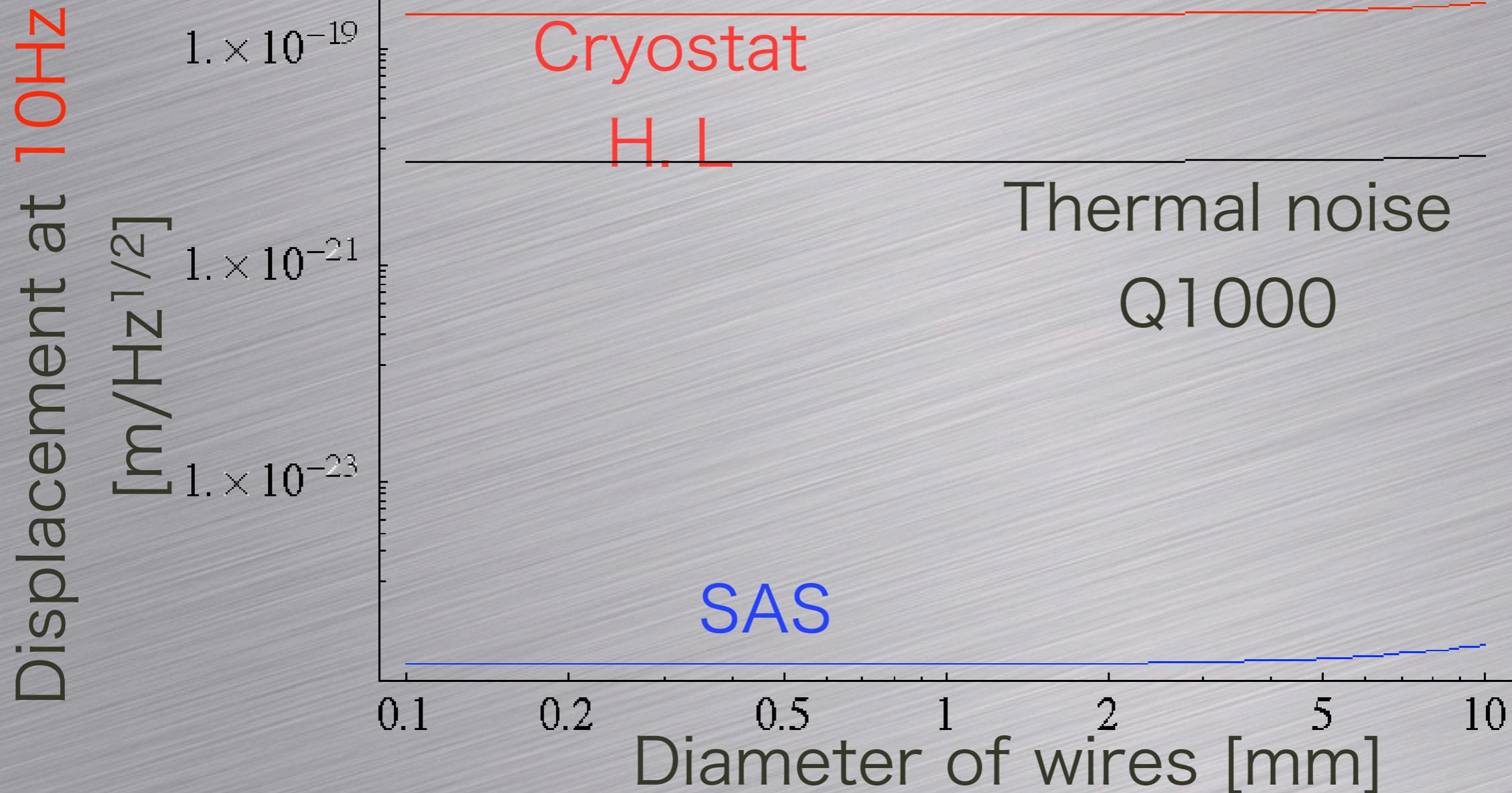
Displacement at 3Hz



not important

Heat link design 11

-10Hz cross H. L. b & c-

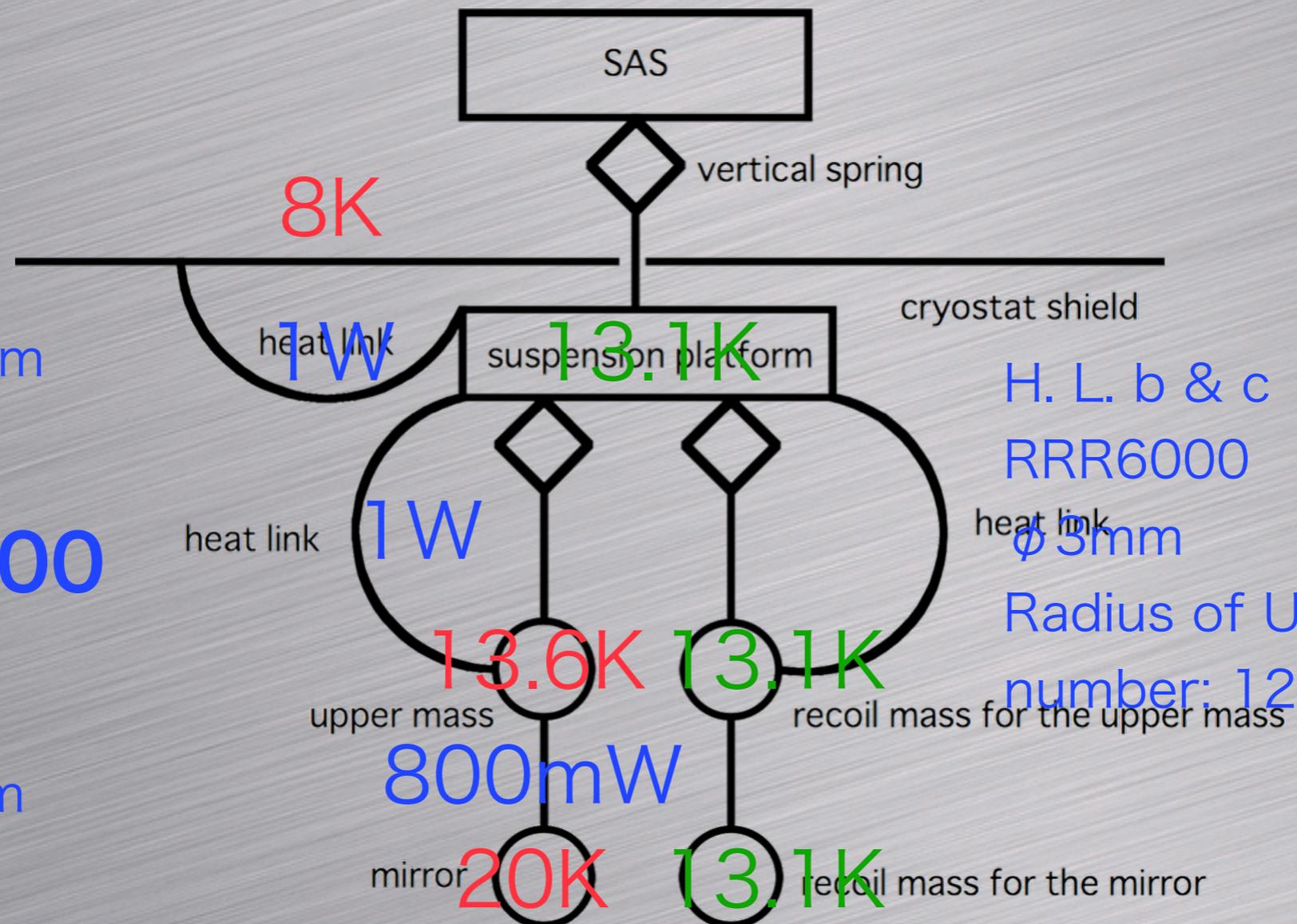


not important

Heat link design 12

-summary of parameter-

3Hz cross



H. L. A

RRR6000

Radius of U: 25cm

$\phi 0.1\text{mm}$

number: 800

Sapphire fiber

4x $\phi 1.8\text{mm} \times 50\text{cm}$

cryostat shield

H. L. b & c

RRR6000

$\phi 3\text{mm}$

Radius of U: 25cm

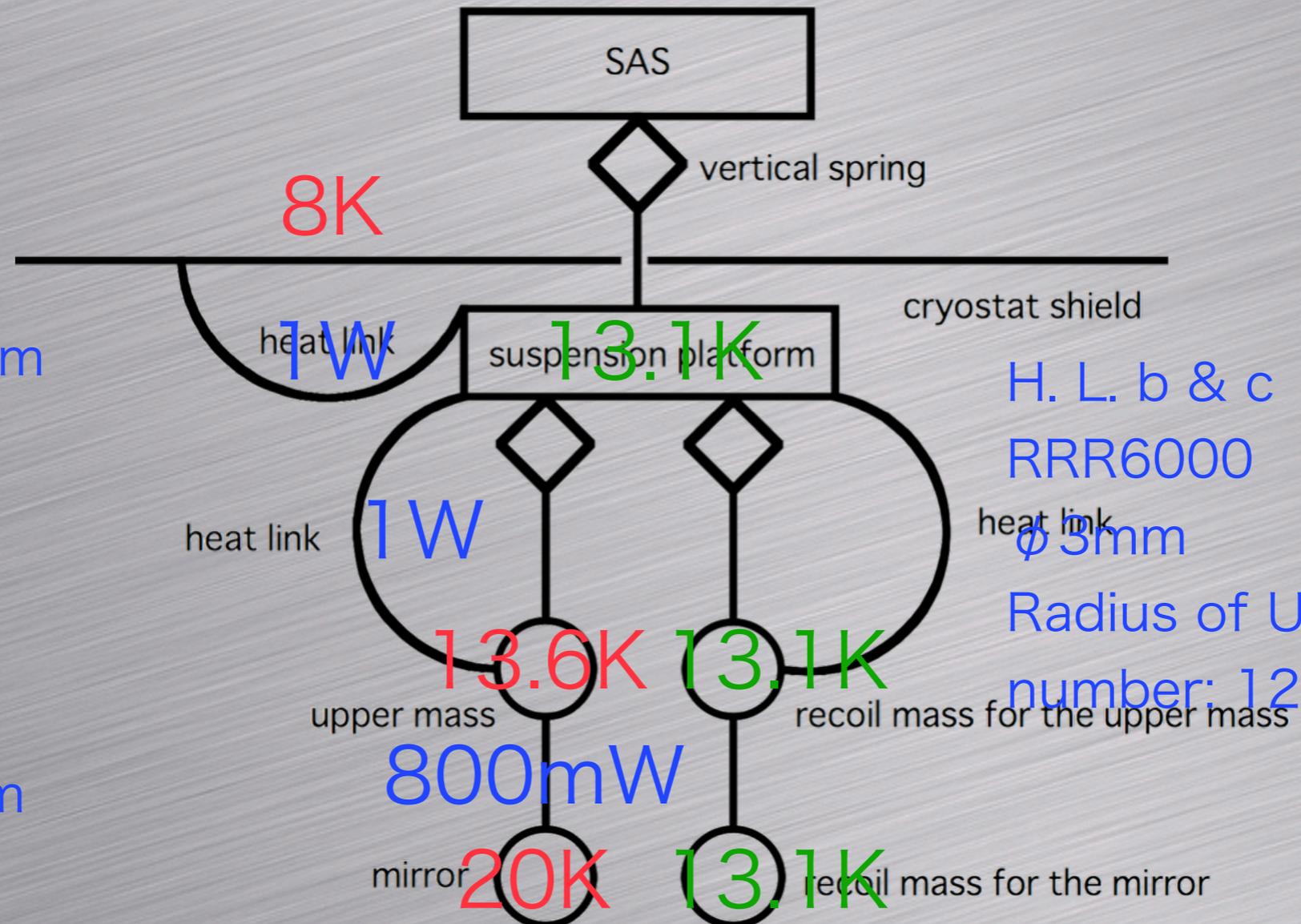
number: 12

800mW

Heat link design 13

-summary of parameter-

10Hz cross



H. L. A

RRR6000

Radius of U: 25cm

ϕ 1mm

number: 8

Sapphire fiber

4x ϕ 1.8mmx50cm

H. L. b & c

RRR6000

heat link

ϕ 3mm

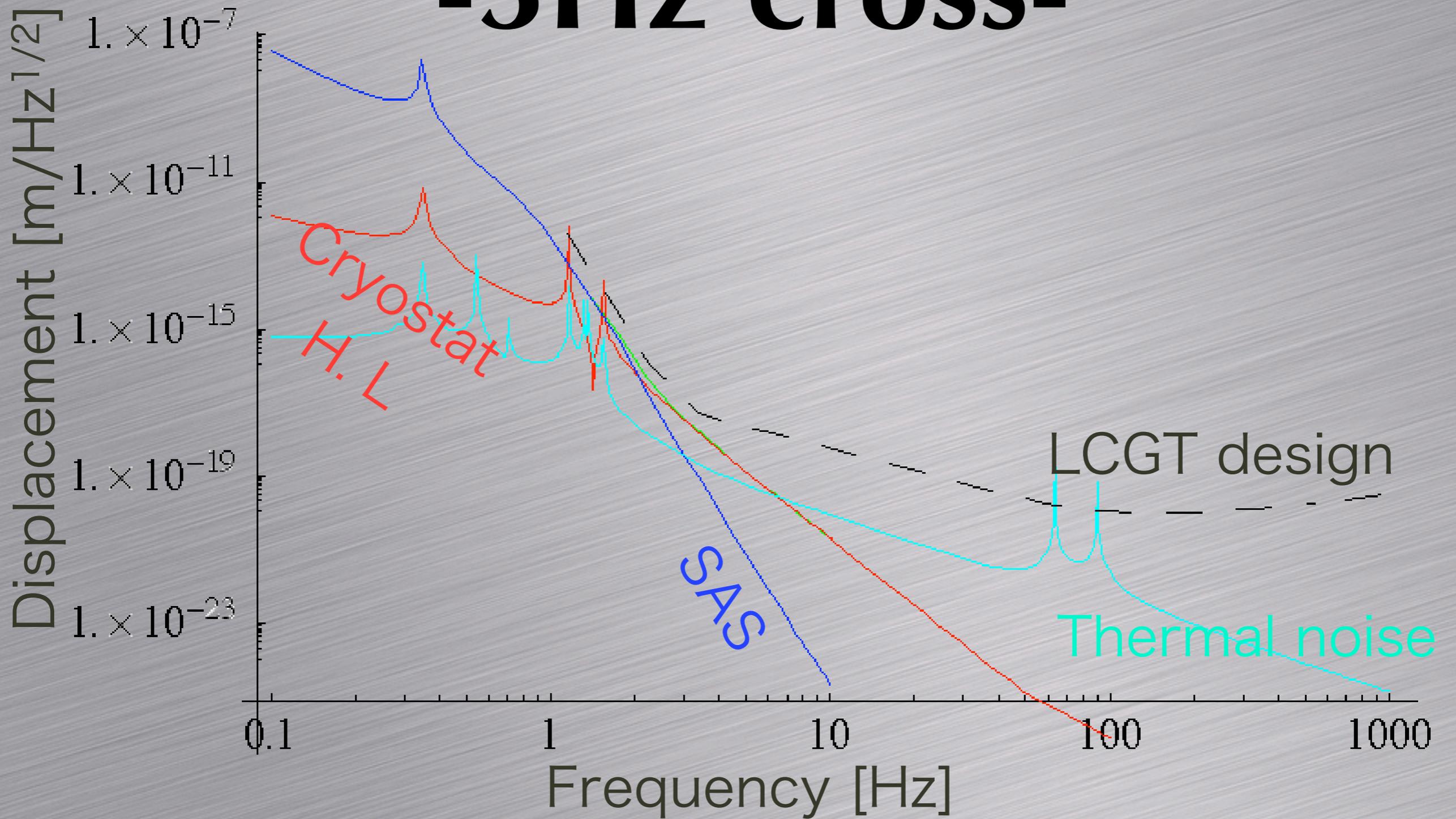
Radius of U: 25cm

number: 12

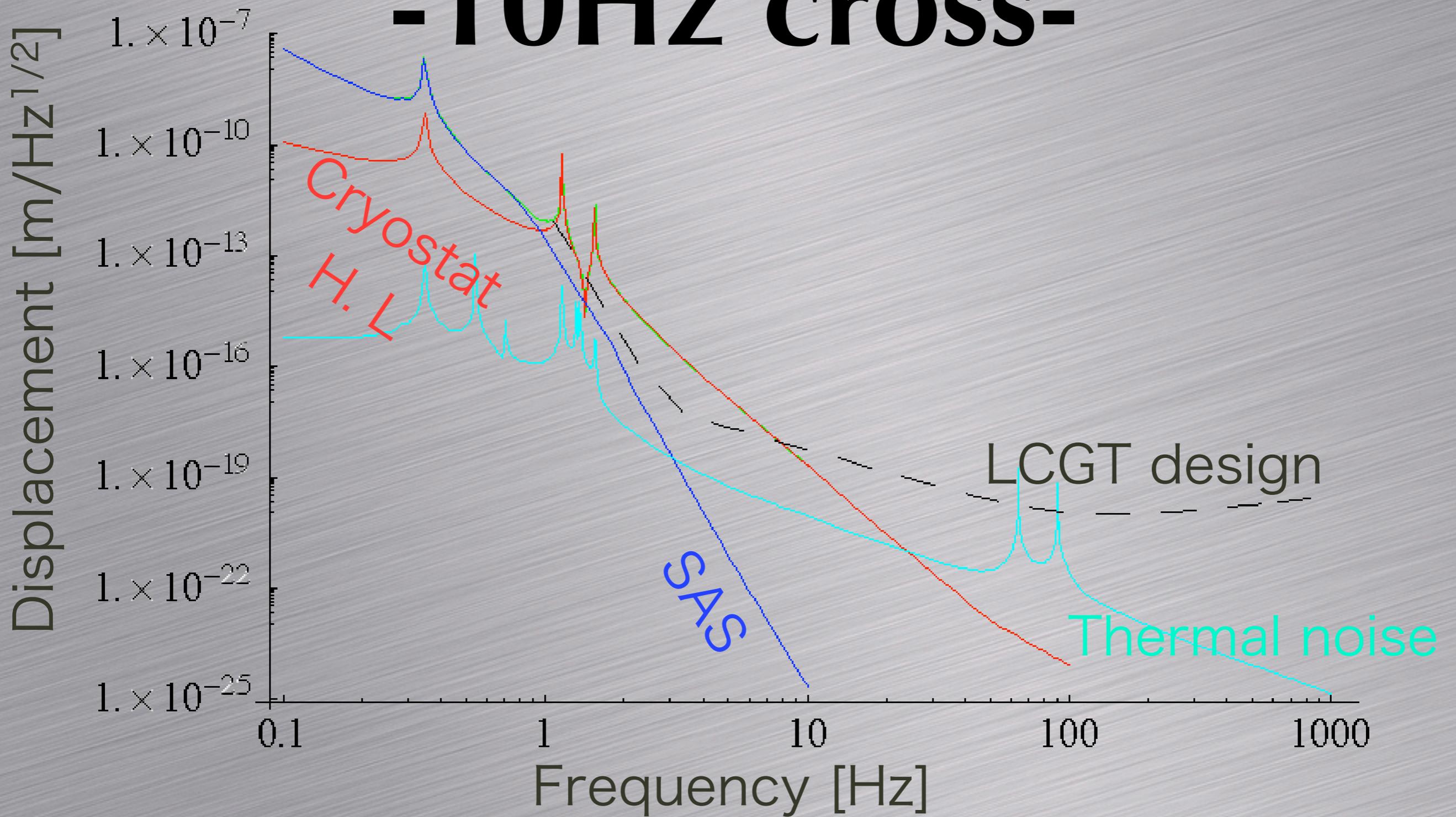
Summary

- Design the heat links for two cases.
 - including design of the cryogenic suspension and temperatures.
- Obviously, 10Hz cross is much easier than 3Hz cross.

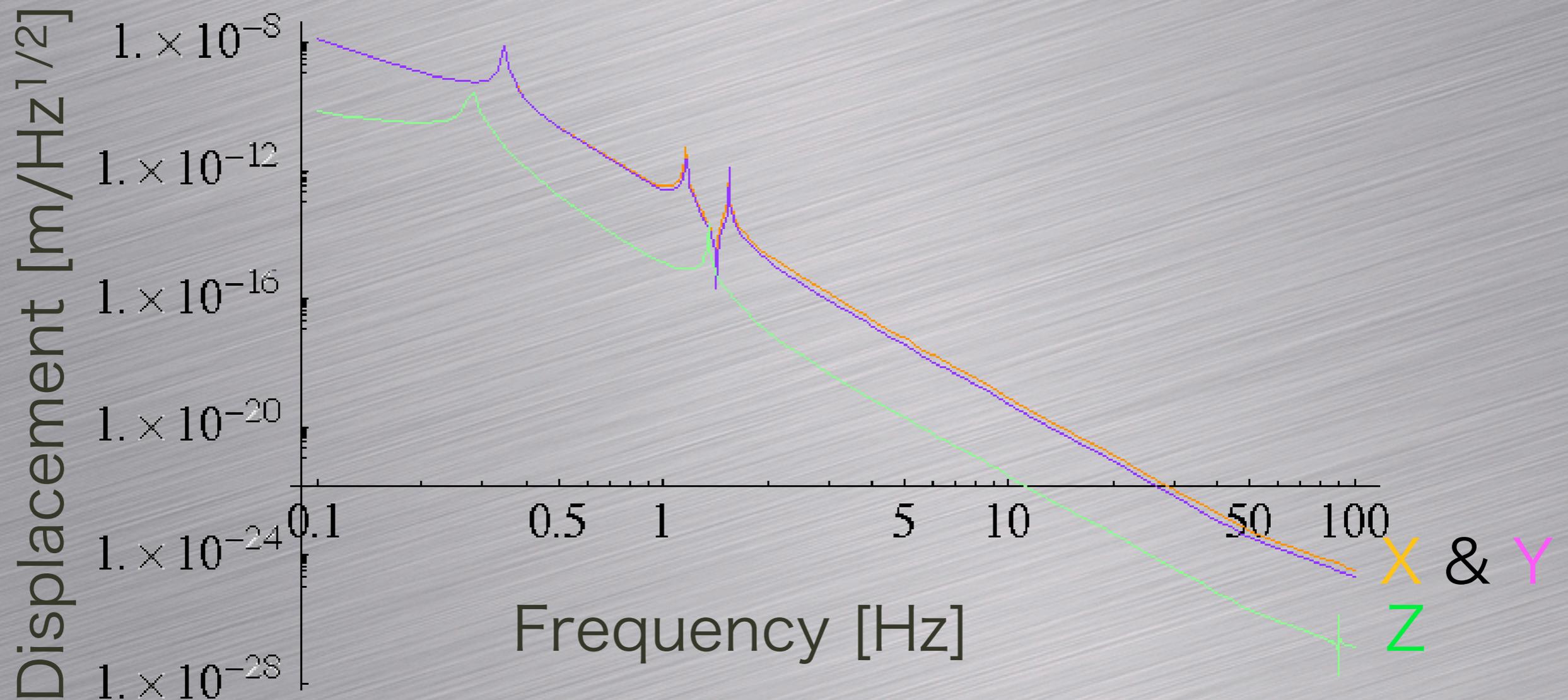
All component -3Hz cross-



All component -10Hz cross-

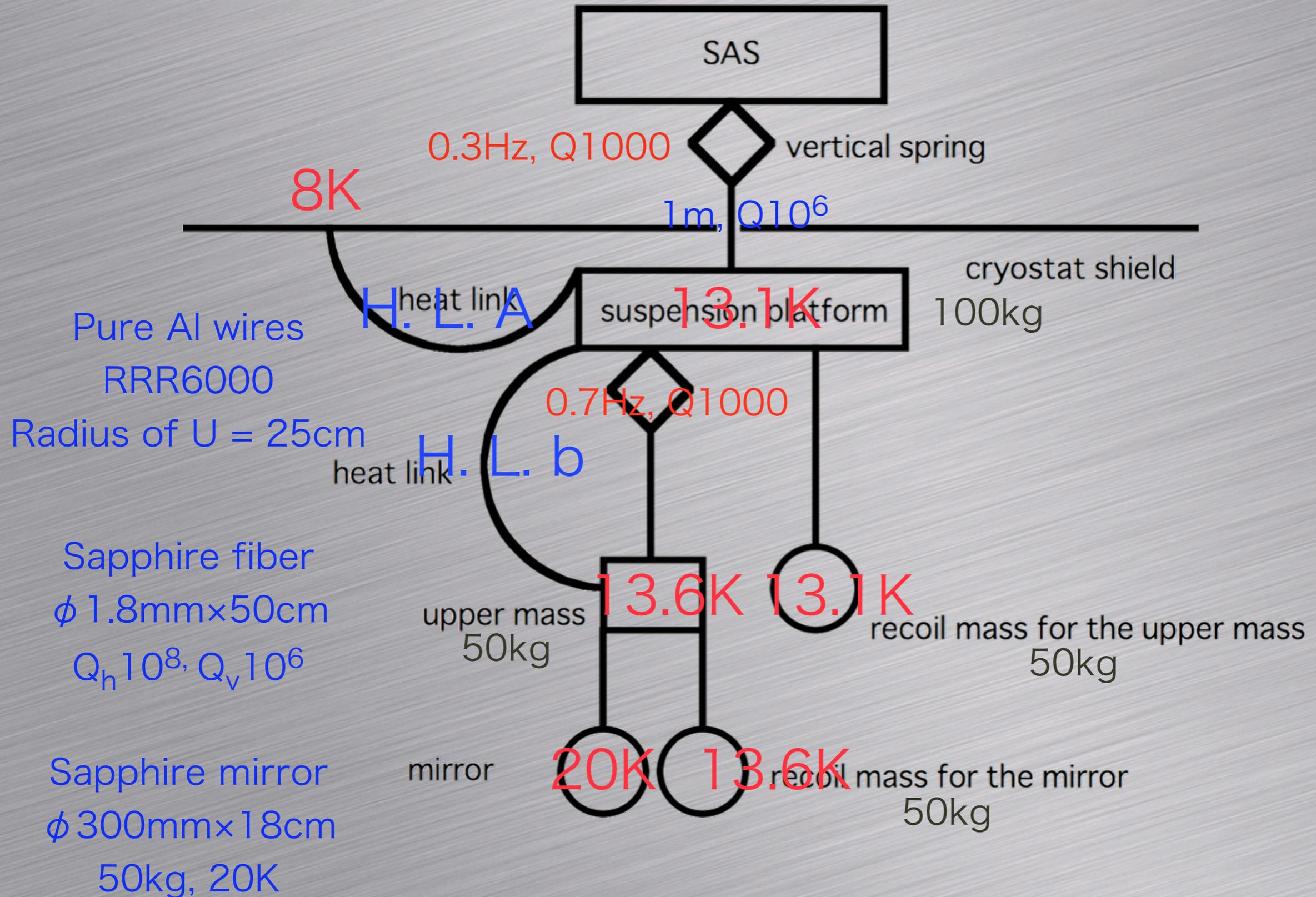


Contribution by each direction



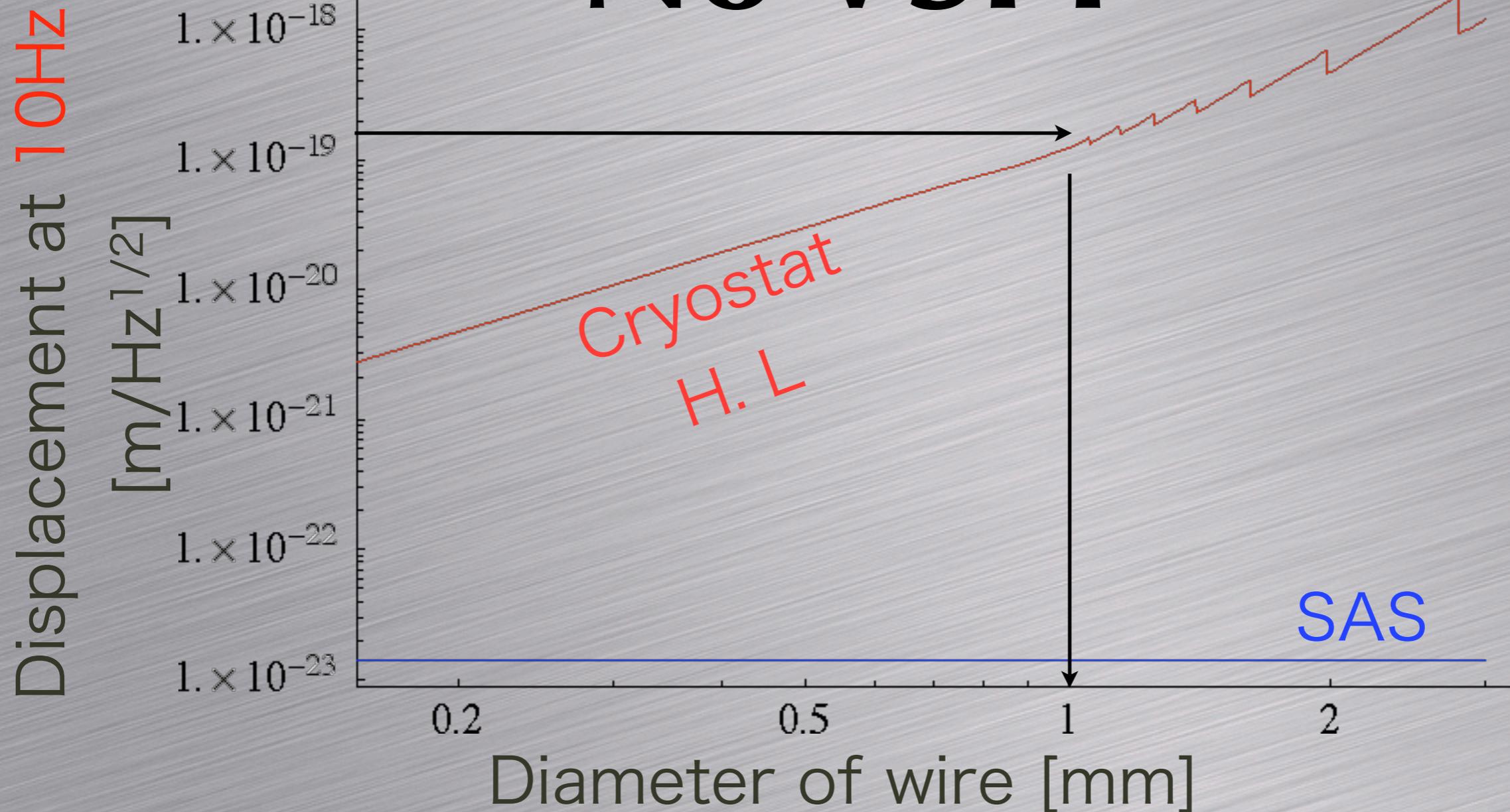
Vertical is not serious.
use VSPI or a mGAS (platform) is enough.

Revised model



With mGAS (0.7 Hz)

-No VSPI-

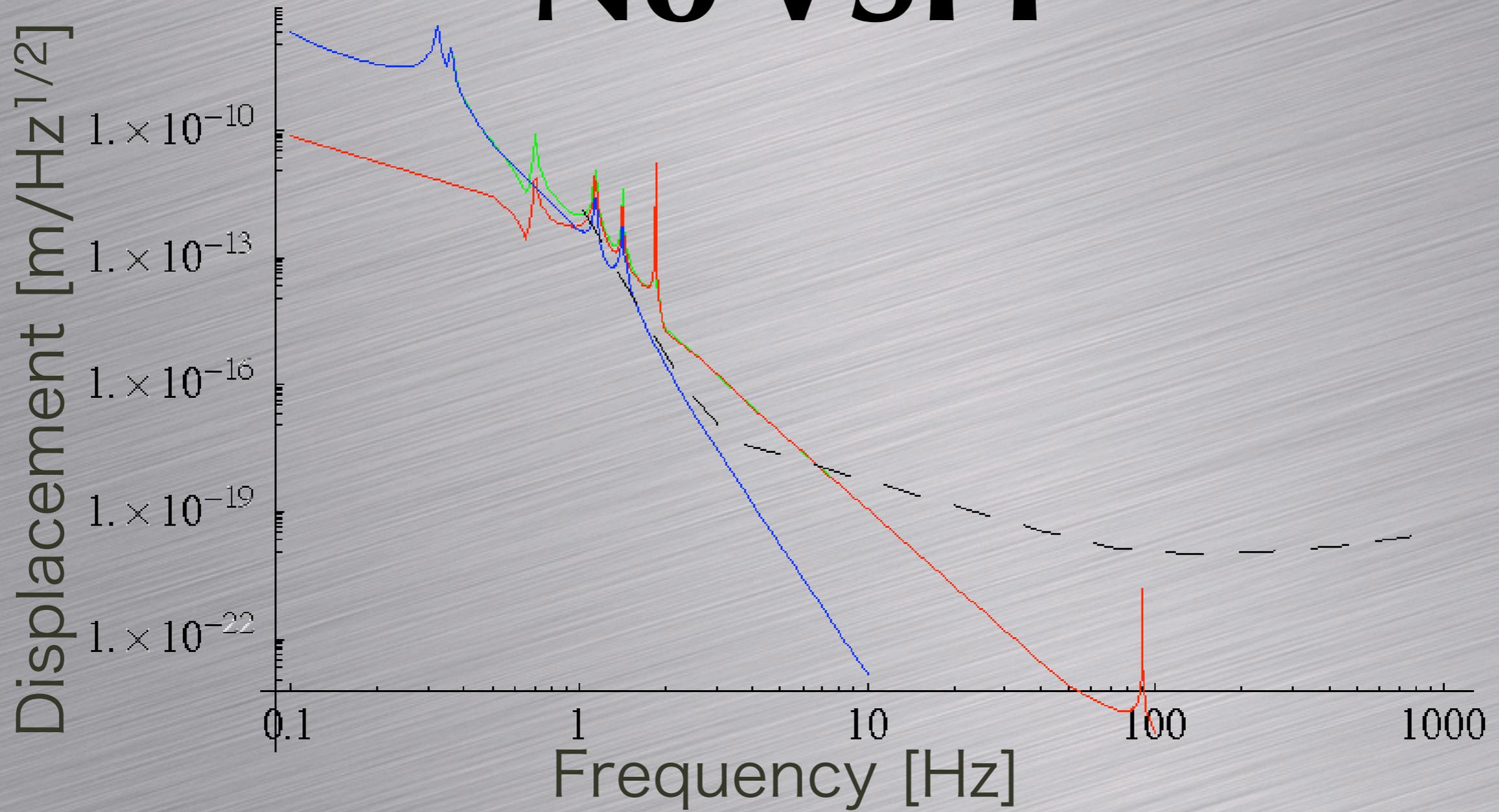


Diameter of 1 mm is satisfied as well as the old model.

Number 8

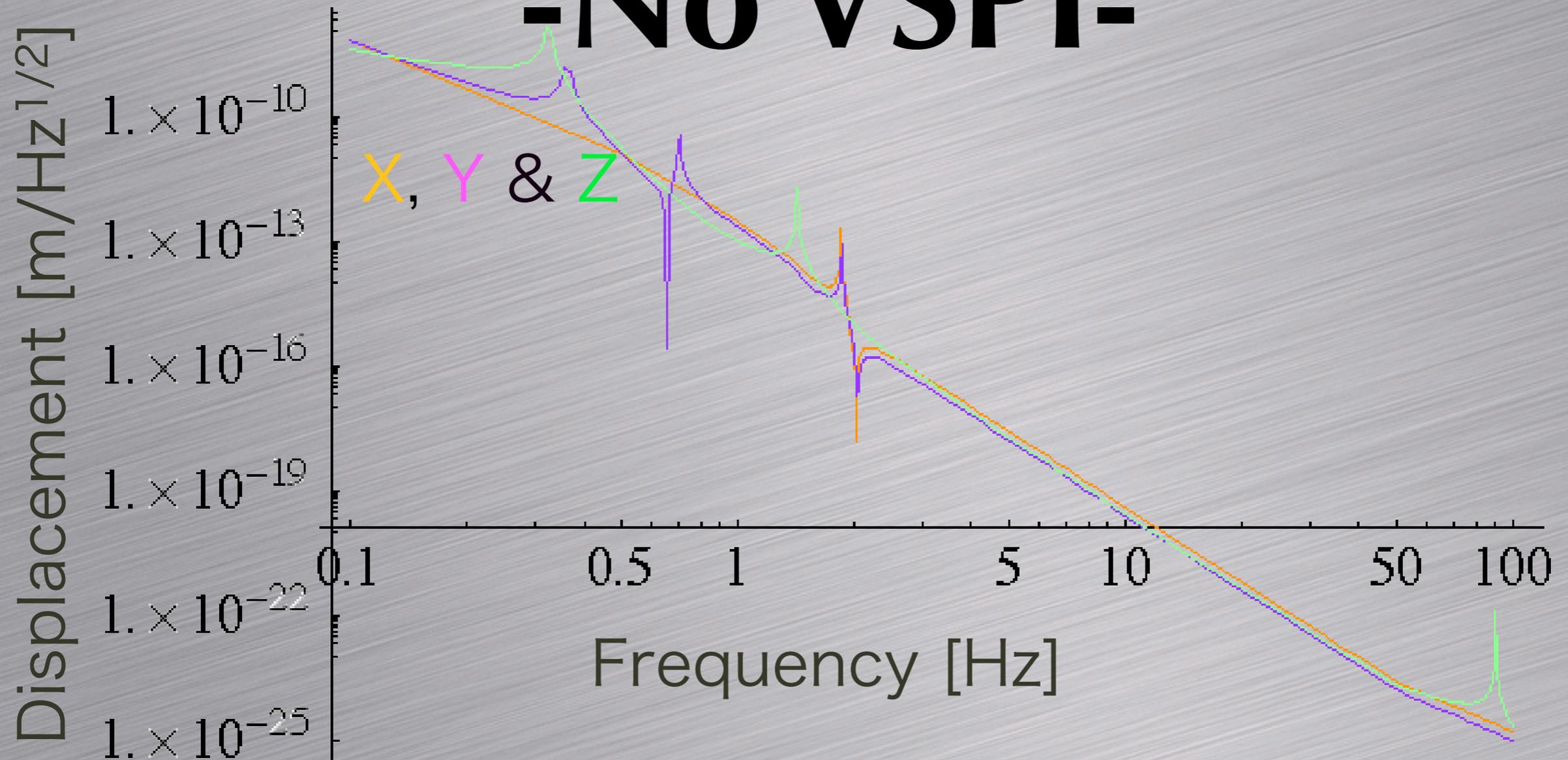
With mGAS (0.7 Hz) 2

-No VSPI-



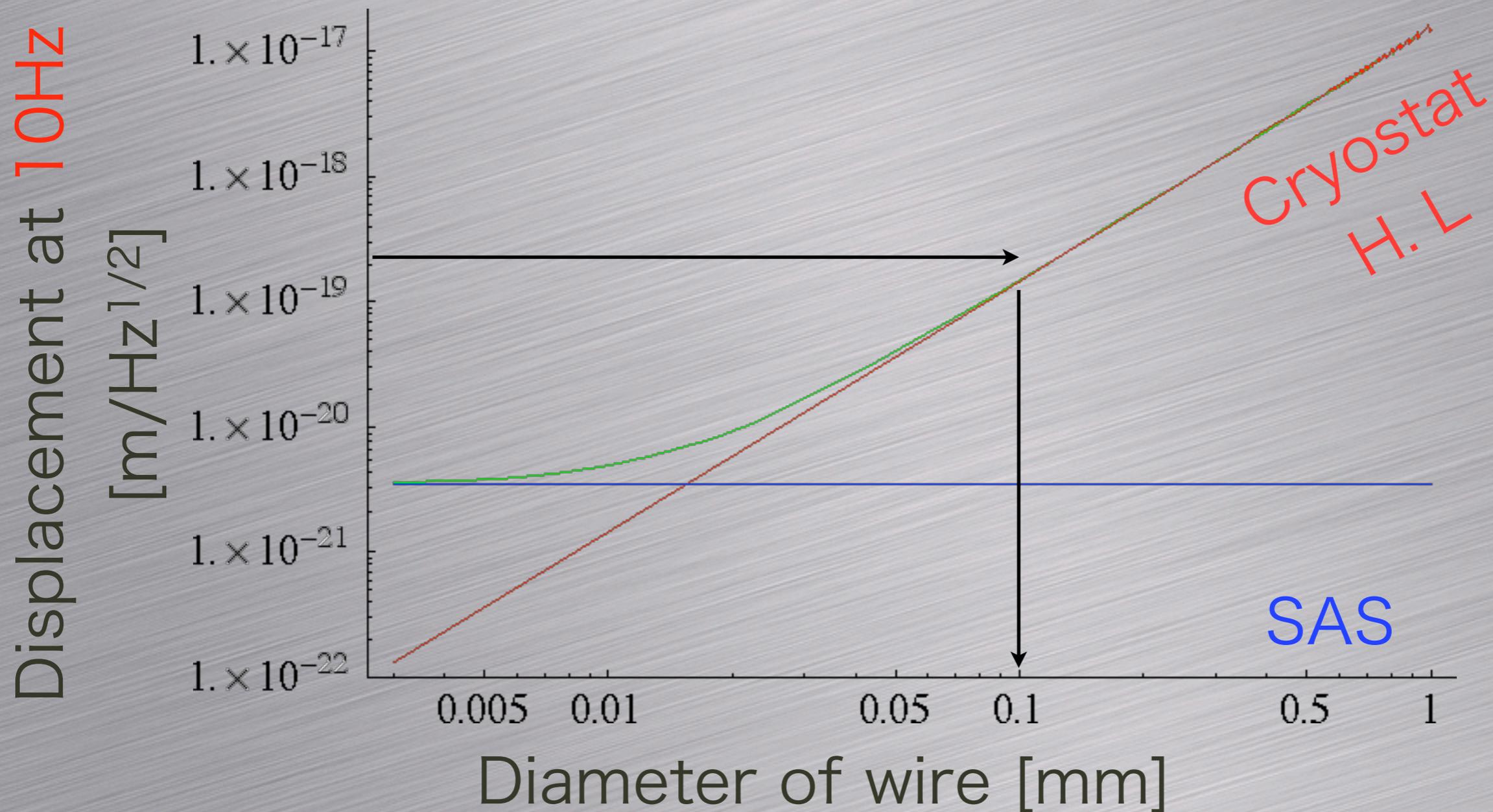
With mGAS (0.7Hz) 3

-No VSPI-



Contribution of all 3 directions are almost the same.

Without mGAS



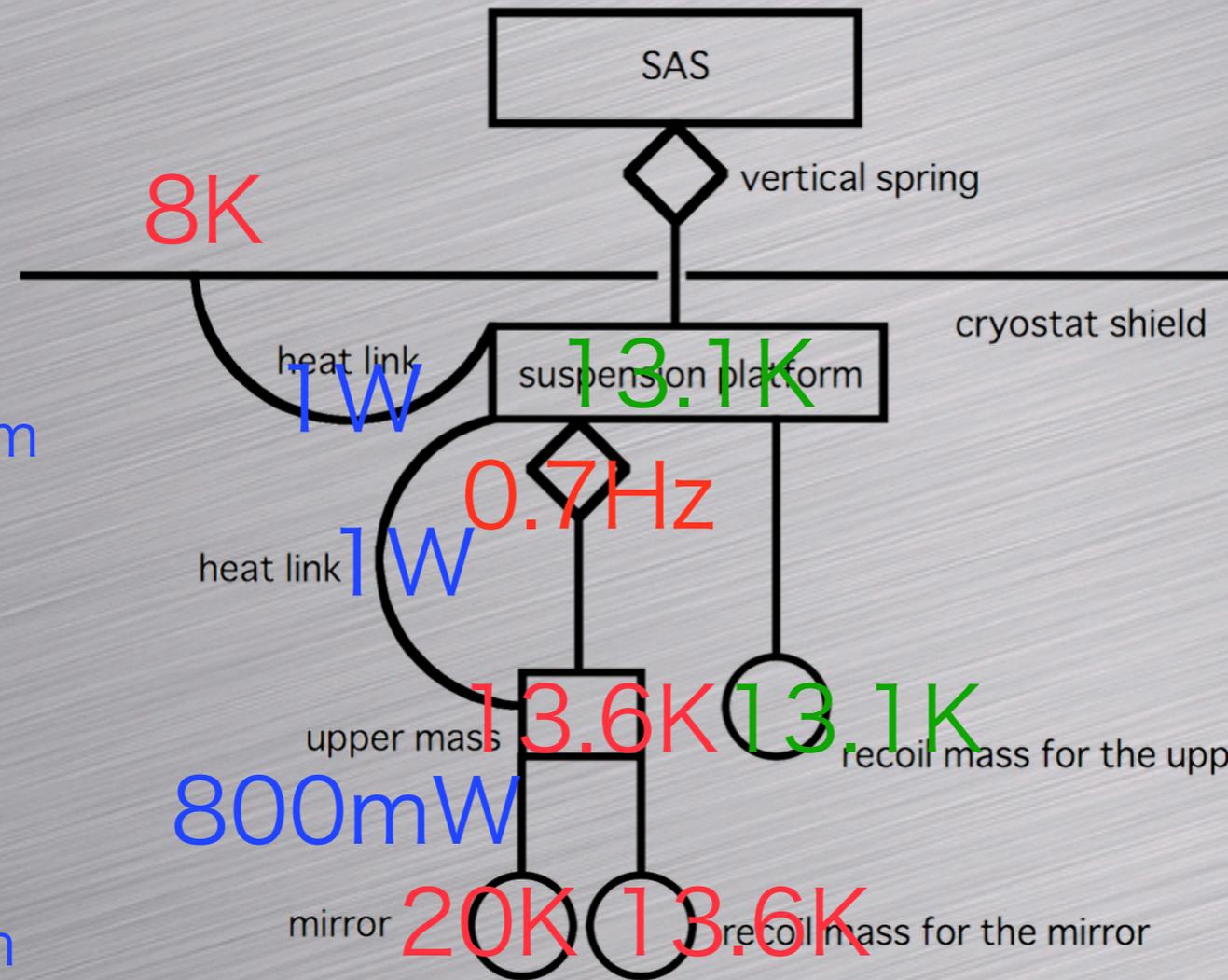
Diameter of **0.1mm** is satisfied.

mGAS in the suspension platform has important roll for vibration isolation of the heat link.

Summary of parameters

New model

No VSPI



H. L. A

RRR6000

Radius of U: 25cm

ϕ 1mm

number: 8

Sapphire fiber

4x ϕ 1.8mmx50cm

H. L. b

RRR6000

ϕ 3mm

Radius of U: 25cm

number: 12

New summary

- Design the heat link for the new model without VSPI.
- VSPI or the mGAS (0.7Hz) in the suspension platform is assisted the heat link design greatly.
- Without VSPI and the mGAS, we should consider an additional vibration isolation stage for the heat link.